Section 16. Electrical Specifications

16.1 Absolute Maximum Ratings

Table 16-1 lists the absolute maximum ratings.

Table 16-1. Absolute Maximum Ratings (Preliminary)

Item		Symbol	Rating	Unit
Supply voltage		V_{CC}	–0.3 to +7.0	V
Programming voltage		V_{PP}	–0.3 to +13.5	V
Input voltage	Ports 1 – 6, 8, 9	V_{in}	–0.3 to V_{CC} + 0.3	V
	Port 7	V_{in}	–0.3 to AVcc + 0.3	V
Analog supply voltage		AVcc	–0.3 to +7.0	V
Analog input voltage		V_{AN}	–0.3 to AVcc + 0.3	V
Operating temperature		T_{opr}	Regular specifications: –20 to +75	°C
			Wide-range specifications: – 40 to +85	°C
Storage temperature		T_{stg}	-55 to +125	°C

Note: Exceeding the absolute maximum ratings shown in table 16-1 can permanently destroy the chip.

16.2 Electrical Characteristics

16.2.1 DC Characteristics

Table 16-2 lists the DC characteristics of the 5V version. Table 16-3 lists the DC characteristics of the 3V version. Table 16-4 gives the allowable current output values of the 5V version. Table 16-5 gives the allowable current output values of the 3V version.

Table 16-2. DC Characteristics (5V Version) (Preliminary)

Conditions: V_{CC} = 5.0V ±10%, AVcc = 5.0V ±10%*, Vss = AVss = 0V,
Ta = –20 to 75°C (regular specifications), Ta = –40 to 85°C (wide-range specifications)

Item		Symbol	Min	Typ	Max	Unit	Measurement conditions
Schmitt trigger input voltage (1)	P67 – P62, P60, P86 – P80, P97, P94 – P90	V_T^-	1.0	–	–	V	
		V_T^+	–	–	Vcc × 0.7	V	
		$V_T^+ - V_T^-$	0.4	–	–	V	
Input High voltage (2)	$\overline{RES}$, $\overline{STBY}$, $\overline{NMI}$ MD1, MD0 EXTAL	V_{IH}	Vcc – 0.7	–	Vcc + 0.3	V	
	P77 – P70		2.0	–	AVcc + 0.3	V	
Input High voltage	Input pins other than (1) and (2)	V_{IH}	2.0	–	Vcc + 0.3	V	
Input Low voltage (3)	$\overline{RES}$, $\overline{STBY}$ MD1, MD0	V_{IL}	–0.3	–	0.5	V	
Input Low voltage	Input pins other than (1) and (3) above	V_{IL}	–0.3	–	0.8	V	
Output High voltage	All output pins	V_{OH}	Vcc – 0.5	–	–	V	I_{OH} = –200µA
			3.5	–	–	V	I_{OH} = –1.0mA
Output Low voltage	All output pins	V_{OL}	–	–	0.4	V	I_{OL} = 1.6mA
	Ports 1 and 2		–	–	1.0	V	I_{OL} = 10.0mA
Input leakage current	$\overline{RES}$	|Iinl	–	–	10.0	µA	V_{in} = 0.5V to Vcc – 0.5V
	$\overline{STBY}$, $\overline{NMI}$, MD1, MD0		–	–	1.0	µA	
	P77 – P70		–	–	1.0	µA	V_{in} = 0.5V to AVcc – 0.5V
Leakage current in 3-state (off state)	Ports 1, 2, 3 4, 5, 6, 8, 9	|ITSI|	–	–	1.0	µA	V_{in} = 0.5V to Vcc – 0.5V
Input pull-up MOS current	Ports 1, 2, 3	-Ip	30	–	250	µA	V_{in} = 0V

Note: * Connect AVcc to the power supply (+5V) even when the A/D and D/A converters are not used.

Table 16-2. DC Characteristics (5V Version) (cont.)

Conditions: V_{CC} = AV_{CC} = 5.0V ±10%, V_{SS} = AV_{SS} = 0V, Ta = –20 to 75°C (regular specifications)
Ta = –40 to 85°C (wide-range specifications)

Item		Symbol	Min	Typ	Max	Unit	Measurement conditions
Input capacitance	$\overline{RES}$ (V_{PP})	C_{in}	–	–	60	pF	V_{in} = 0V
	$\overline{NMI}$		–	–	30	pF	f = 1MHz
	All input pins except $\overline{RES}$ and $\overline{NMI}$		–	–	15	pF	Ta = 25°C
Current dissipation*1	Normal operation	I_{CC}	–	12	25	mA	f = 6MHz
			–	16	30	mA	f = 8MHz
			–	20	40	mA	f = 10MHz
	Sleep mode		–	8	15	mA	f = 6MHz
			–	10	20	mA	f = 8MHz
			–	12	25	mA	f = 10MHz
	Standby modes*2		–	0.01	5.0	µA	
Analog supply current	During A/D or D/A conversion	AI_{CC}	–	2.0	5.0	mA	
	Waiting		–	0.01	5.0	µA	
RAM standby voltage		V_{RAM}	2.0	–	–	V	

Notes: *1 Current dissipation values assume that $V_{IH\ min}$ = V_{CC} – 0.5V, $V_{IL\ max}$ = 0.5V, all output pins are in the no-load state, and all input pull-up transistors are off.

*2 For these values it is assumed that $V_{RAM} \leq V_{CC} < 4.5V$ and $V_{IH\ min}$ = V_{CC} × 0.9, $V_{IL\ max}$ = 0.3V.

Table 16-3. DC Characteristics (3V Version) (preliminary)

Conditions: V_{CC} = 3.0V ±10%, AVcc = 5.0V ±10%*1, Vss = AVss = 0V, Ta = –20 to 70°C

Item		Symbol	Min	Typ	Max	Unit	Measurement conditions
Schmitt trigger input voltage*2 (1)	P67 – P62, P60, P86 – P80, P97, P94 – P90	V_{T^-}	$V_{CC} \times 0.15$	–	–	V	
		V_{T^+}	–	–	$V_{CC} \times 0.7$	V	
		$V_{T^+} - V_{T^-}$	0.2	–	–	V	
Input High voltage*2 (2)	$\overline{RES}$, $\overline{STBY}$ MD1, MD0 EXTAL, $\overline{NMI}$	V_{IH}	$V_{CC} \times 0.9$	–	$V_{CC} + 0.3$	V	
	P77 – P70		$V_{CC} \times 0.7$	–	$AV_{CC} + 0.3$	V	
	Input pins other than (1) and (2) above		$V_{CC} \times 0.7$	–	$V_{CC} + 0.3$	V	
Input Low voltage*2 (3)	$\overline{RES}$, $\overline{STBY}$ MD1, MD0	V_{IL}	–0.3	–	$V_{CC} \times 0.1$	V	
	Input pins other than (1) and (3) above		–0.3	–	$V_{CC} \times 0.15$	V	
Output High voltage	All output pins	V_{OH}	$V_{CC} - 0.4$	–	–	V	I_{OH} = –200µA
			$V_{CC} - 0.9$	–	–	V	I_{OH} = –1.0mA
Output Low voltage	All output pins	V_{OL}	–	–	0.4	V	I_{OL} = 0.8mA
	Ports 1 and 2		–	–	0.4	V	I_{OL} = 1.6mA
Input leakage current	$\overline{RES}$	$\lvert I_{in} \rvert$	–	–	10.0	µA	V_{in} = 0.5 to V_{CC} – 0.5V
	$\overline{STBY}$, $\overline{NMI}$, MD1, MD0		–	–	1.0	µA	
	P77 – P70		–	–	1.0	µA	V_{in} = 0.5 to AV_{CC} – 0.5V
Leakage current in 3-state (off state)	Ports 1, 2, 3 4, 5, 6, 8, 9	$\lvert I_{TSI} \rvert$	–	–	1.0	µA	V_{in} = 0.5 to V_{CC} – 0.5V
Input pull-up MOS current	Ports 1, 2, 3	$-I_P$	3	–	120	µA	V_{in} = 5.0V

Notes: *1 Connect AVcc to the power supply (+3V) even when the A/D converter is not used.

*2 In the range 3.3V < Vcc < 4.5V, for the input levels of V_{IH} and V_{T^+}, apply the higher of the values given for the 5V and 3V versions. For V_{IL} and V_{T^-}, apply the lower of the values given for the 5V and 3V versions.

Table 16-3. DC Characteristics (3V Version) (preliminary) (cont.)

Conditions: V_{CC} = 3.0V ±10%, AVCC = 5.0V ±10%*1, V_{SS} = AVss = 0V, Ta = –20 to 70°C

Item		Symbol	Min	Typ	Max	Unit	Measurement conditions
Input capacitance	$\overline{RES}$	C_{in}	–	–	60	pF	V_{in} = 0V
	$\overline{NMI}$		–	–	30	pF	f = 1MHz
	All input pins except $\overline{RES}$ and $\overline{NMI}$		–	–	15	pF	Ta = 25°C
Current dissipation*1	Normal operation	I_{CC}	–	6	–	mA	f = 3MHz
			–	10	20	mA	f = 5MHz
	Sleep mode		–	4	–	mA	f = 3MHz
			–	6	12	mA	f = 5MHz
	Standby modes*2		–	0.01	5.0	µA	
Analog supply current	During A/D or D/A conversion	AIcc	–	2.0	5.0	mA	
	Waiting		–	0.01	5.0	µA	
RAM backup voltage (in standby modes)		V_{RAM}	2.0	–	–	V	

Notes: *1 Current dissipation values assume that $V_{IH\ min}$ = V_{CC} – 0.5V, $V_{IL\ max}$ = 0.5V, all output pins are in the no-load state, and all input pull-up transistors are off.

*2 For these values it is assumed that $V_{RAM} \leq V_{CC} < 2.7V$ and $V_{IH\ min} = V_{CC} \times 0.9$, $V_{IL\ max}$ = 0.3V.

Table 16-4. Allowable Output Current Sink Values (5V Version) (Preliminary)

Conditions: V_{CC} = AV_{CC} = 5.0V ±10%, V_{SS} = AV_{SS} = 0V, Ta = –20 to 75°C (regular specifications)
Ta = –40 to 85°C (wide-range specifications)

Item		Symbol	Min	Typ	Max	Unit
Allowable output Low current sink (per pin)	Ports 1 and 2	I_{OL}	–	–	10	mA
	Other output pins		–	–	2.0	mA
Allowable output Low current sink (total)	Ports 1 and 2, total	ΣI_{OL}	–	–	80	mA
	Total of all output		–	–	120	mA
Allowable output High current sink (per pin)	All output pins	$-I_{OH}$	–	–	2.0	mA
Allowable output High current sink (total)	Total of all output	$\Sigma-I_{OH}$	–	–	40	mA

Table 16-5. Allowable Output Current Sink Values (3V Version) (Preliminary)

Conditions: V_{CC} = 3.0V ±10%, AV_{CC} = 5.0V ±10%, V_{SS} = AV_{SS} = 0V, Ta = –20 to 75°C

Item		Symbol	Min	Typ	Max	Unit
Allowable output Low current sink (per pin)	Ports 1 and 2	I_{OL}	–	–	2	mA
	Other output pins		–	–	1	mA
Allowable output Low current sink (total)	Ports 1 and 2, total	ΣI_{OL}	–	–	40	mA
	Total of all output		–	–	60	mA
Allowable output High current sink (per pin)	All output pins	$-I_{OH}$	–	–	2	mA
Allowable output High current sink (total)	Total of all output	$\Sigma-I_{OH}$	–	–	30	mA

Note: To avoid degrading the reliability of the chip, be careful not to exceed the output current sink values in tables 16-4 and 16-5. In particular, when driving a Darlington transistor pair or LED directly, be sure to insert a current-limiting resistor in the output path. See figures 16-1 and 16-2.

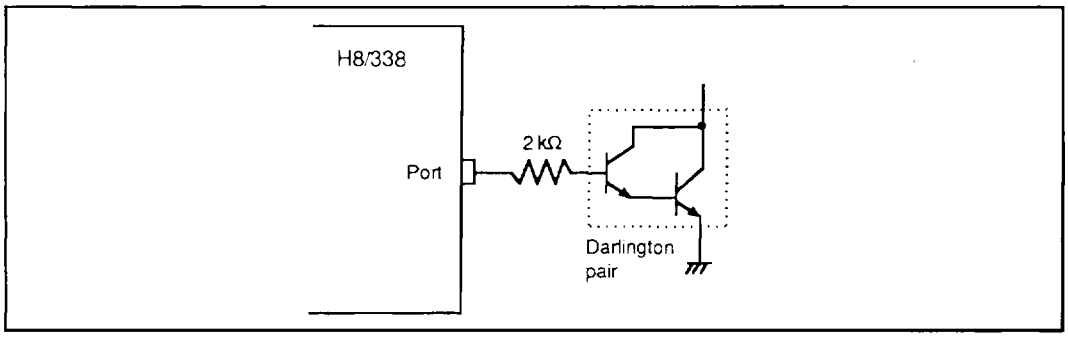

Figure 16-1. Example of Circuit for Driving a Darlington Pair (5V Version)

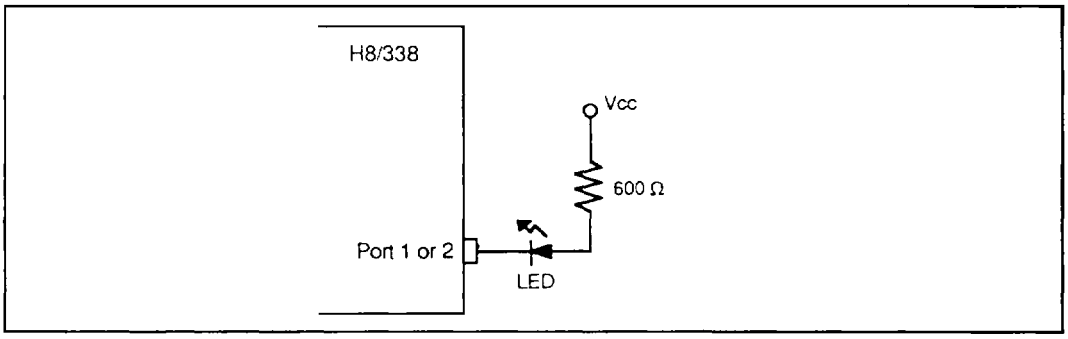

Figure 16-2. Example of Circuit for Driving an LED (5V Version)

16.2.2 AC Characteristics

The AC characteristics are listed in three tables. Bus timing parameters are given in table 16-6, control signal timing parameters in table 16-7, and timing parameters of the on-chip supporting modules in table 16-8.

Table 16-6. Bus Timing (Preliminary)

Condition A: V_{CC} = 5.0V ±10%, V_{SS} = 0V, Ø = 0.5MHz to maximum operating frequency,
Ta = –20 to 75°C (regular specifications),
Ta = –40 to 85°C (wide-range specifications)

Condition B: V_{CC} = 3.0V ±10%, V_{SS} = 0V, Ø = 0.5MHz to maximum operating frequency,
Ta = –20 to 75°C

		Condition B		Condition A							
		5MHz		6MHz		8MHz		10MHz			Measurement
Item	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	conditions
Clock cycle time	t_{cyc}	200	2000	166.7	2000	125	2000	100	2000	ns	Fig. 16-4
Clock pulse width Low	t_{CL}	70	–	65	–	45	–	35	–	ns	Fig. 16-4
Clock pulse width High	t_{CH}	70	–	65	–	45	–	35	–	ns	Fig. 16-4
Clock rise time	t_{Cr}	–	25	–	15	–	15	–	15	ns	Fig. 16-4
Clock fall time	t_{Cf}	–	25	–	15	–	15	–	15	ns	Fig. 16-4
Address delay time	t_{AD}	–	90	–	70	–	60	–	50	ns	Fig. 16-4
Address hold time	t_{AH}	30	–	30	–	25	–	20	–	ns	Fig. 16-4
Address strobe delay time	t_{ASD}	–	80	–	70	–	60	–	40	ns	Fig. 16-4
Write strobe delay time	t_{WSD}	–	80	–	70	–	60	–	50	ns	Fig. 16-4
Strobe delay time	t_{SD}	–	90	–	70	–	60	–	50	ns	Fig. 16-4
Write strobe pulse width*	t_{WSW}	200	–	200	–	150	–	120	–	ns	Fig. 16-4
Address setup time 1*	t_{AS1}	25	–	25	–	20	–	15	–	ns	Fig. 16-4
Address setup time 2*	t_{AS2}	105	–	105	–	80	–	65	–	ns	Fig. 16-4
Read data setup time	t_{RDS}	90	–	70	–	50	–	35	–	ns	Fig. 16-4
Read data hold time*	t_{RDH}	0	–	0	–	0	–	0	–	ns	Fig. 16-4
Read data access time*	t_{ACC}	–	300	–	270	–	210	–	170	ns	Fig. 16-4
Write data delay time	t_{WDD}	–	125	–	85	–	75	–	75	ns	Fig. 16-4
Write data setup time	t_{WDS}	10	–	20	–	10	–	5	–	ns	Fig. 16-4
Write data hold time	t_{WDH}	30	–	30	–	25	–	20	–	ns	Fig. 16-4
Wait setup time	t_{WTS}	60	–	40	–	40	–	40	–	ns	Fig. 16-5
Wait hold time	t_{WTH}	20	–	10	–	10	–	10	–	ns	Fig. 16-5

Note: * Values at maximum operating frequency

Table 16-7. Control Signal Timing (Preliminary)

Condition A: V_{CC} = 5.0V ±10%, V_{SS} = 0V, Ø = 0.5MHz to maximum operating frequency,
Ta = –20 to 75°C (regular specifications),
Ta = –40 to 85°C (wide-range specifications)

Condition B: V_{CC} = 3.0V ±10%, V_{SS} = 0V, Ø = 0.5MHz to maximum operating frequency,
Ta = –20 to 75°C

		Condition B		Condition A							
		5MHz		6MHz		8MHz		10MHz			Measurement
Item	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	conditions
$\overline{RES}$ setup time	t_{RESS}	300	–	200	–	200	–	200	–	ns	Fig. 16-6
$\overline{RES}$ pulse width	t_{RESW}	10	–	10	–	10	–	10	–	tcyc	Fig. 16-6
$\overline{NMI}$ setup time ($\overline{NMI}$, $\overline{IRQ_0}$ to $\overline{IRQ_7}$)	t_{NMIS}	300	–	150	–	150	–	150	–	ns	Fig. 16-7
$\overline{NMI}$ hold time ($\overline{NMI}$, $\overline{IRQ_0}$ to $\overline{IRQ_7}$)	t_{NMIH}	10	–	10	–	10	–	10	–	ns	Fig. 16-7
Interrupt pulse width for recovery from software standby mode ($\overline{NMI}$, $\overline{IRQ_0}$ to $\overline{IRQ_2}$)	t_{NMIW}	300	–	200	–	200	–	200	–	ns	Fig. 16-7
Crystal oscillator settling time (reset)	t_{OSC1}	20	–	20	–	20	–	20	–	ms	Fig. 16-8
Crystal oscillator settling time (software standby)	t_{OSC2}	10	–	10	–	10	–	10	–	ms	Fig. 16-9

Table 16-8. Timing Conditions of On-Chip Supporting Modules (Preliminary)

Condition A: V_{CC} = 5.0V ±10%, V_{SS} = 0V, Ø = 0.5MHz to maximum operating frequency,
Ta = –20 to 75°C (regular specifications),
Ta = –40 to 85°C (wide-range specifications)

Condition B: V_{CC} = 3.0V ±10%, V_{SS} = 0V, Ø = 0.5MHz to maximum operating frequency,
Ta = –20 to 75°C

			Condition B		Condition A							
			5MHz		6MHz		8MHz		10MHz			Measurement
Item		Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	conditions
FRT	Timer output delay time	t_{FTOD}	–	150	–	100	–	100	–	100	ns	Fig. 16-10
	Timer input setup time	t_{FTIS}	80	–	50	–	50	–	50	–	ns	Fig. 16-10
	Timer clock input setup time	t_{FTCS}	80	–	50	–	50	–	50	–	ns	Fig. 16-11
	Timer clockpulse width	t_{FTCWH} t_{FTCWL}	1.5	–	1.5	–	1.5	–	1.5	–	t_{cyc}	Fig. 16-11
TMR	Timer output delay time	t_{TMOD}	–	150	–	100	–	100	–	100	ns	Fig. 16-12
	Timer reset input setup time	t_{TMRS}	80	–	50	–	50	–	50	–	ns	Fig. 16-14
	Timer clock input setup time	t_{TMCS}	80	–	50	–	50	–	50	–	ns	Fig. 16-13
	Timer clock pulse width (single edge)	t_{TMCWH}	1.5	–	1.5	–	1.5	–	1.5	–	t_{cyc}	Fig. 16-13
	Timer clock pulse width (both edges)	t_{TMCWL}	2.5	–	2.5	–	2.5	–	2.5	–	t_{cyc}	Fig. 16-13
PWM	Timer output delay time	t_{PWOD}	–	150	–	100	–	100	–	100	ns	Fig. 16-15
SCI	Input clock cycle (Async)	t_{Scyc}	2	–	2	–	2	–	2	–	t_{cyc}	Fig. 16-16
	(Sync)	t_{Scyc}	6	–	6	–	6	–	6	–	t_{cyc}	Fig. 16-16
	Transmit data delay time (Sync)	t_{TXD}	–	200	–	100	–	100	–	100	ns	Fig. 16-16
	Receive data setup time (Sync)	t_{RXS}	150	–	100	–	100	–	100	–	ns	Fig. 16-16
	Receive data hold time (Sync)	t_{RXH}	150	–	100	–	100	–	100	–	ns	Fig. 16-16
	Input clock pulse width	t_{SCKW}	0.4	0.6	0.4	0.6	0.4	0.6	0.4	0.6	t_{Scyc}	Fig. 16-17
Ports	Output data delay time	t_{PWD}	–	150	–	100	–	100	–	100	ns	Fig. 16-18
	Input data setup time	t_{PRS}	80	–	50	–	50	–	50	–	ns	Fig. 16-18
	Input data hold time	t_{PRH}	80	–	50	–	50	–	50	–	ns	Fig. 16-18

• **Measurement Conditions for AC Characteristics**

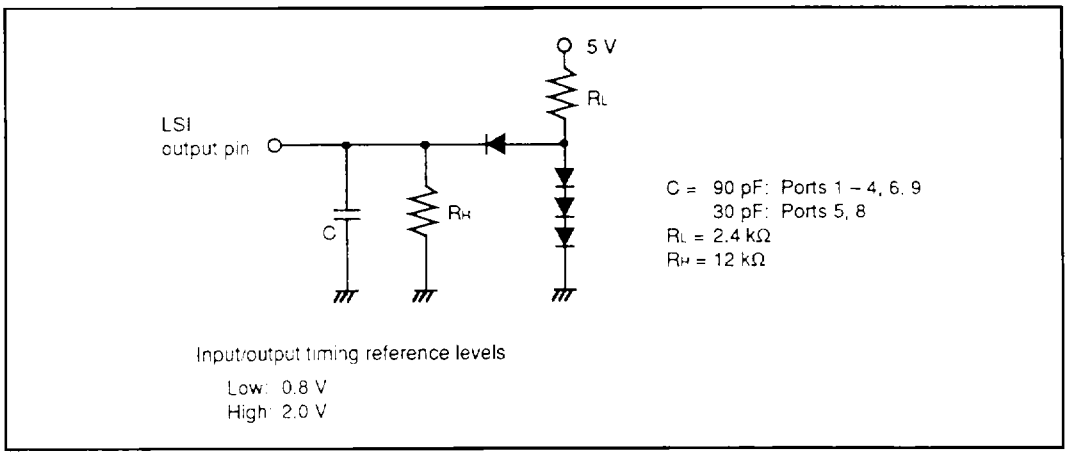

Figure 16-3. Output Load Circuit

16.2.3 A/D Converter Characteristics

Table 16-9 lists the characteristics of the on-chip A/D converter.

Table 16-9. A/D Converter Characteristics (Preliminary)

Condition A: V_{CC} = 5.0V ±10%, AV_{CC} = 5.0V ±10%, V_{SS} = AV_{SS} = 0V, Ø = 0.5MHz to maximum operating frequency, Ta = –20 to 75°C (regular specifications), Ta = –40 to 85°C (wide-range specifications)

Condition B: V_{CC} = 3.0V ±10%, AV_{CC} = 5.0V ±10%, V_{SS} = AV_{SS} = 0V, Ø = 0.5MHz to maximum operating frequency, Ta = –20 to 75°C

	Condition B			Condition A									
	5MHz			6MHz			8MHz			10MHz			
Item	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Unit
Resolution	8	8	8	8	8	8	8	8	8	8	8	8	Bits
Conversion time (single mode)*	—	—	24.4	—	—	20.4	—	—	15.25	—	—	12.2	µs
Analog input capacitance	—	—	20	—	—	20	—	—	20	—	—	20	pF
Allowable signal source impedance	—	—	10	—	—	10	—	—	10	—	—	10	kΩ
Nonlinearity error	—	—	±1	—	—	±1	—	—	±1	—	—	±1	LSB
Offset error	—	—	±1	—	—	±1	—	—	±1	—	—	±1	LSB
Full-scale error	—	—	±1	—	—	±1	—	—	±1	—	—	±1	LSB
Quantizing error	—	—	±0.5	—	—	±0.5	—	—	±0.5	—	—	±0.5	LSB
Absolute accuracy	—	—	±1.5	—	—	±1.5	—	—	±1.5	—	—	±1.5	LSB

Note: * Values at maximum operating frequency

16.2.4 D/A Converter Characteristics

Table 16-10 lists the characteristics of the on-chip D/A converter.

Table 16-10. D/A Converter Characteristics

Condition A: V_{CC} = 5.0V ±10%, AV_{CC} = 5.0V ±10%, V_{SS} = AV_{SS} = 0V, Ø = 0.5MHz to maximum operating frequency, Ta = –20 to 75°C (regular specifications), Ta = –40 to 85°C (wide-range specifications)

Condition B: V_{CC} = 3.0V ±10%, AV_{CC} = 5.0V ±10%, V_{SS} = AV_{SS} = 0V, Ø = 0.5MHz to maximum operating frequency, Ta = –20 to 75°C

	Condition B			Condition A										
	5MHz			6MHz			8MHz			10MHz				Measurement
Item	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Unit	conditions
Resolution	8	8	8	8	8	8	8	8	8	8	8	8	Bits	
Conversion time	—	—	10.0	—	—	10.0	—	—	10.0	—	—	10.0	µs	30pF load capacitance
Absolute accuracy	—	±1	±1.5	—	±1	±1.5	—	±1	±1.5	—	±1	±1.5	LSB	2MΩ load resistance
	—	—	±1	—	—	±1	—	—	±1	—	—	±1	LSB	4MΩ load resistance

16.3 MCU Operational Timing

This section provides the following timing charts:

16.3.1 Bus Timing	Figures 16-4 to 16-5
16.3.2 Control Signal Timing	Figures 16-6 to 16-9
16.3.3 16-Bit Free-Running Timer Timing	Figures 16-10 to 16-11
16.3.4 8-Bit Timer Timing	Figures 16-12 to 16-14
16.3.5 PWM Timer Timing	Figure 16-15
16.3.6 SCI Timing	Figures 16-16 to 16-17
16.3.7 I/O Port Timing	Figure 16-18

16.3.1 Bus Timing

(1) Basic Bus Cycle (without Wait States) in Expanded Modes

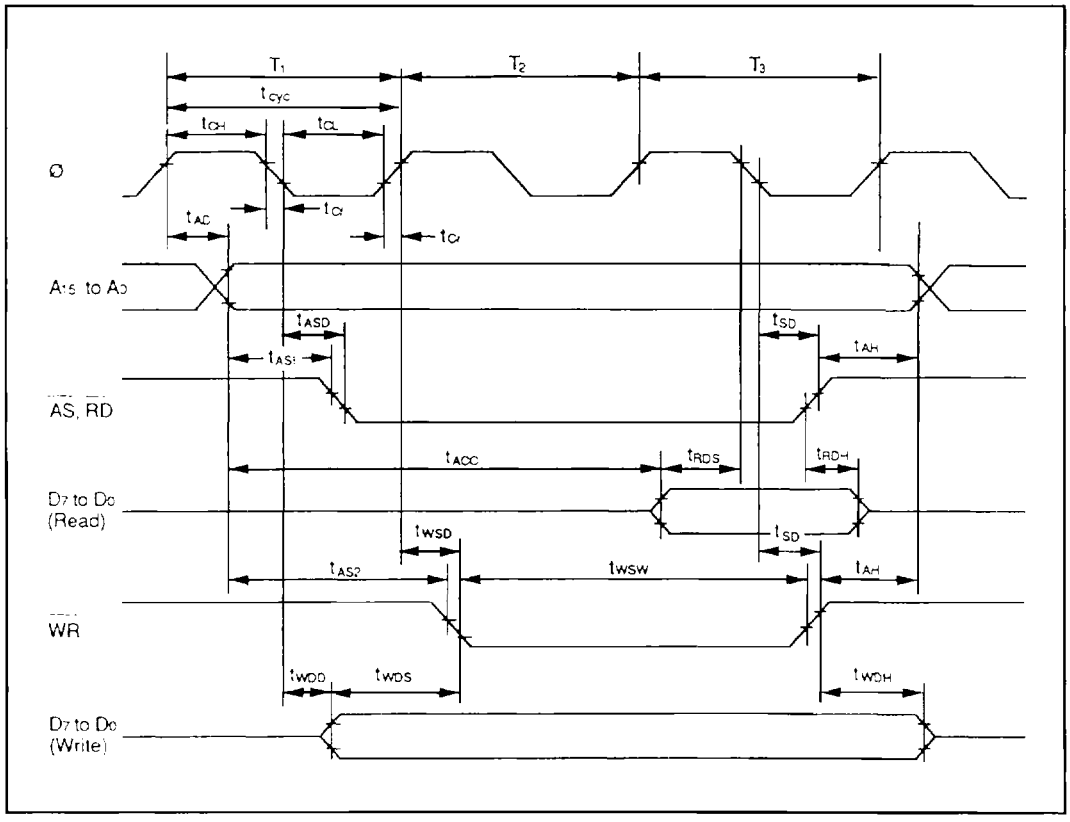

Figure 16-4. Basic Bus Cycle (without Wait States) in Expanded Modes

(2) Basic Bus Cycle (with 1 Wait State) in Expanded Modes

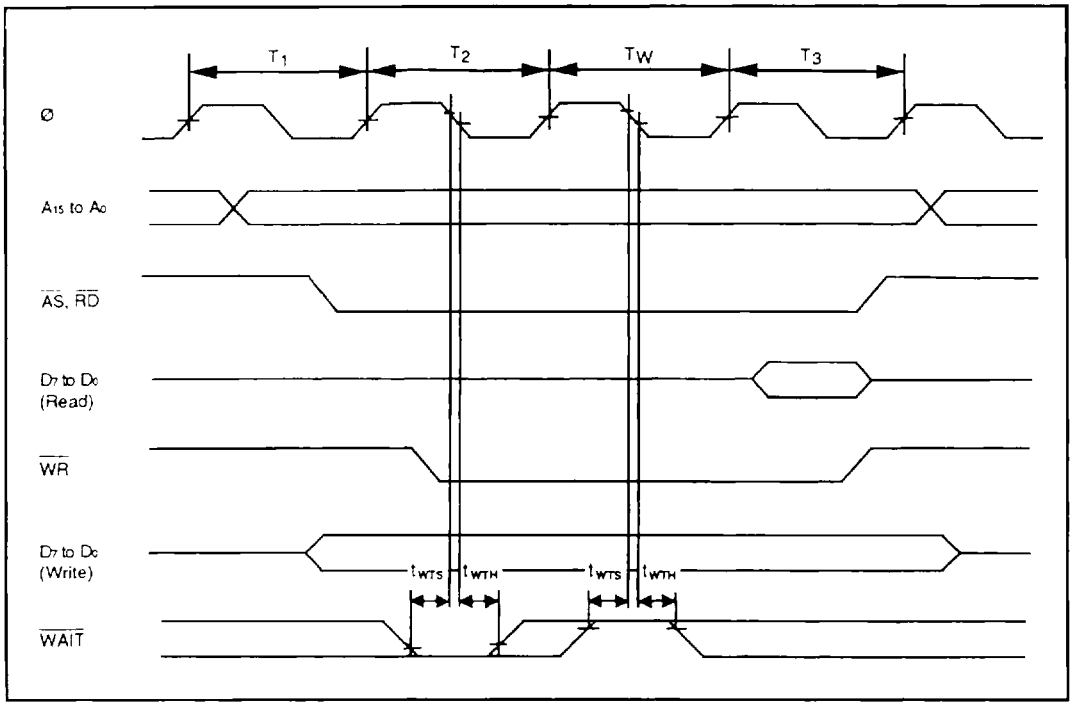

Figure 16-5. Basic Bus Cycle (with 1 Wait State) in Expanded Modes

16.3.2 Control Signal Timing

(1) Reset Input Timing

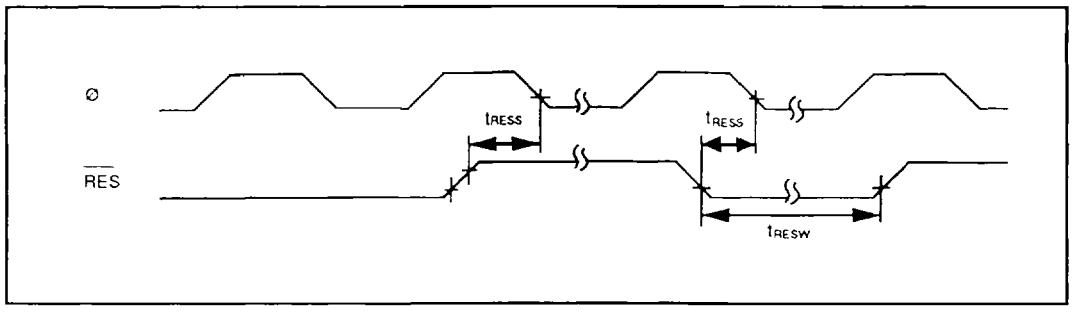

Figure 16-6. Reset Input Timing

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(2) Interrupt Input Timing

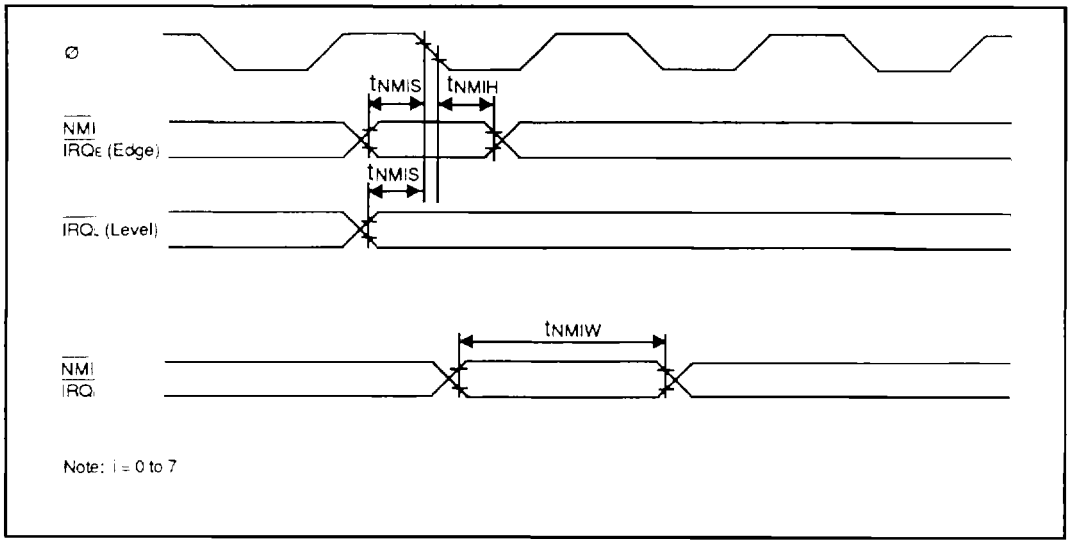

Figure 16-7. Interrupt Input Timing

(3) Clock Settling Timing

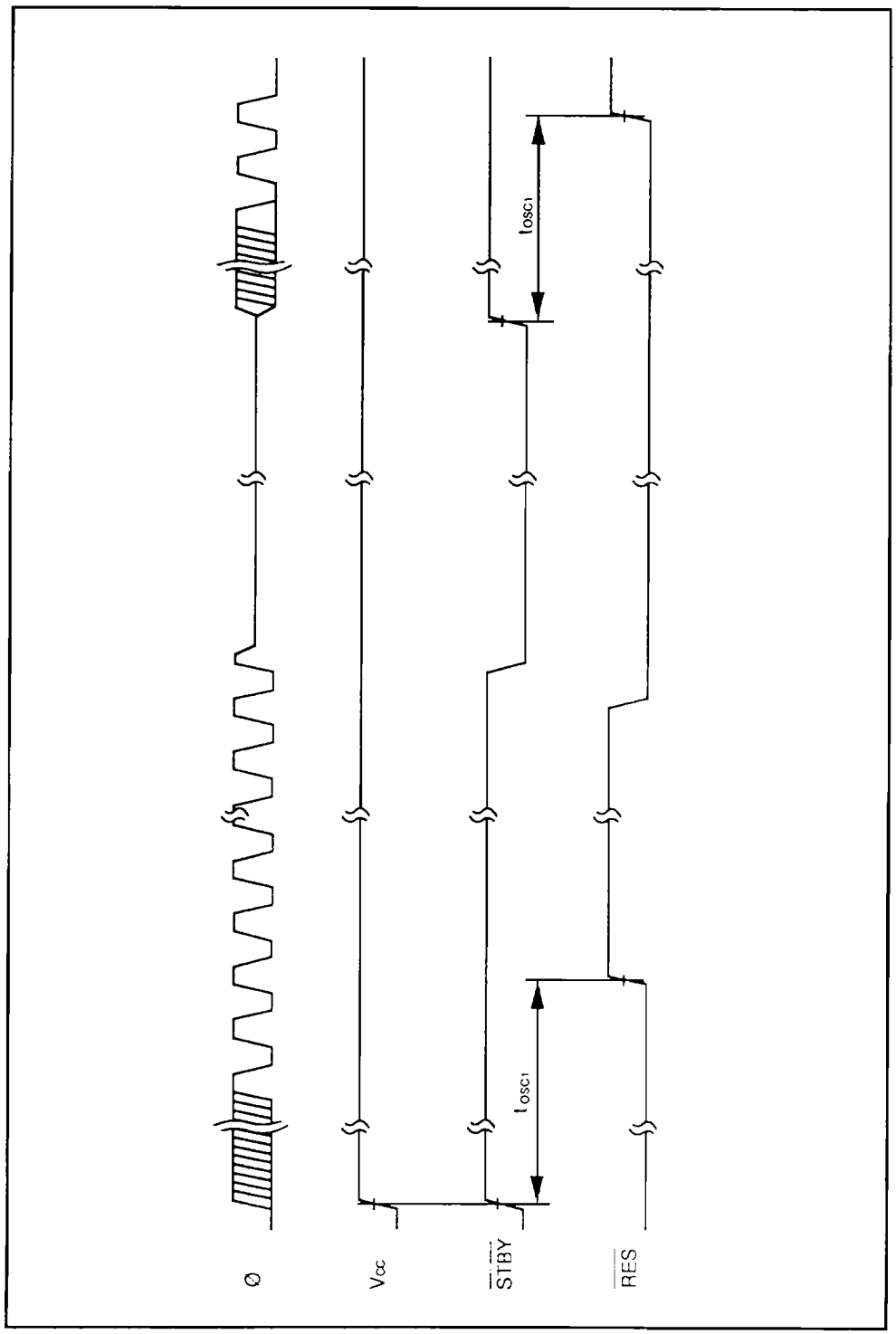

Figure 16-8. Clock Settling Timing

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(4) Clock Settling Timing for Recovery from Software Standby Mode

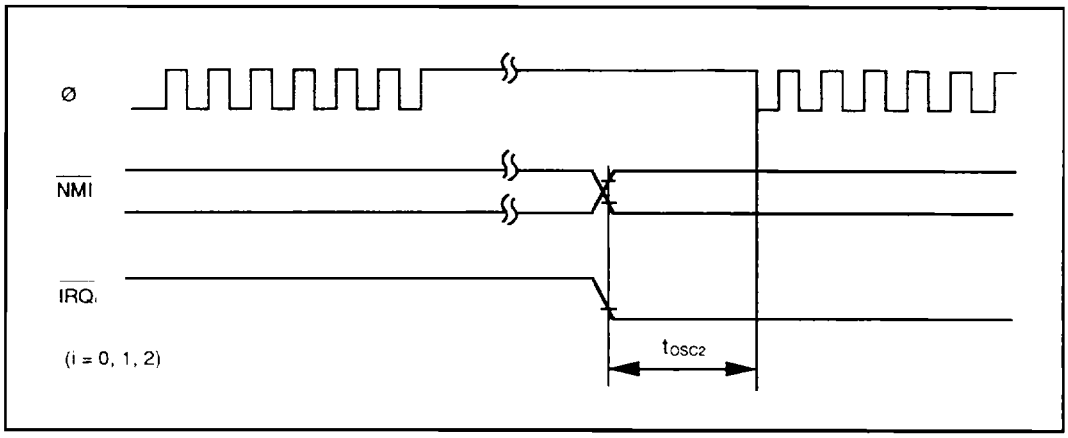

Figure 16-9. Clock Settling Timing for Recovery from Software Standby Mode

16.3.3 16-Bit Free-Running Timer Timing

(1) Free-Running Timer Input/Output Timing

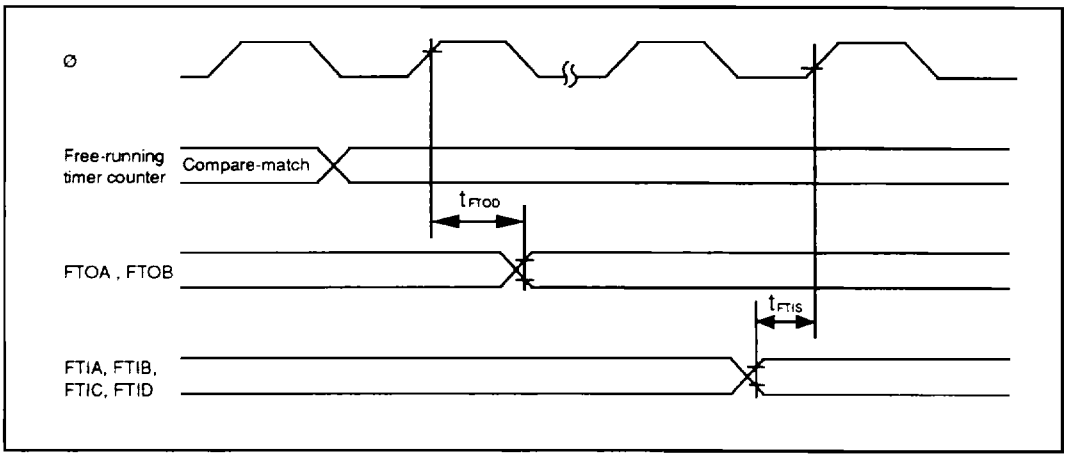

Figure 16-10. Free-Running Timer Input/Output Timing

(2) External Clock Input Timing for Free-Running Timer

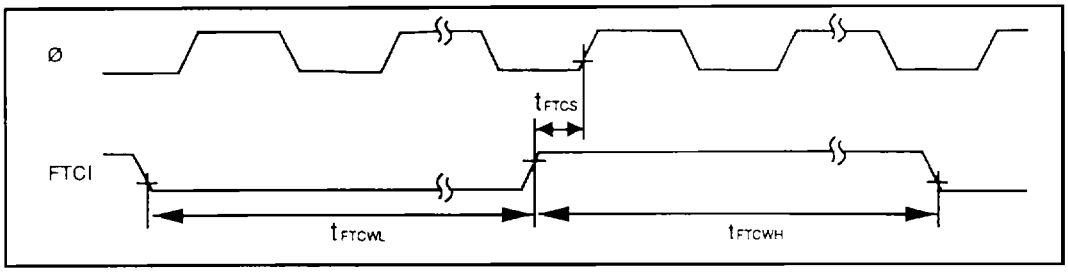

Figure 16-11. External Clock Input Timing for Free-Running Timer

16.3.4 8-Bit Timer Timing

(1) 8-Bit Timer Output Timing

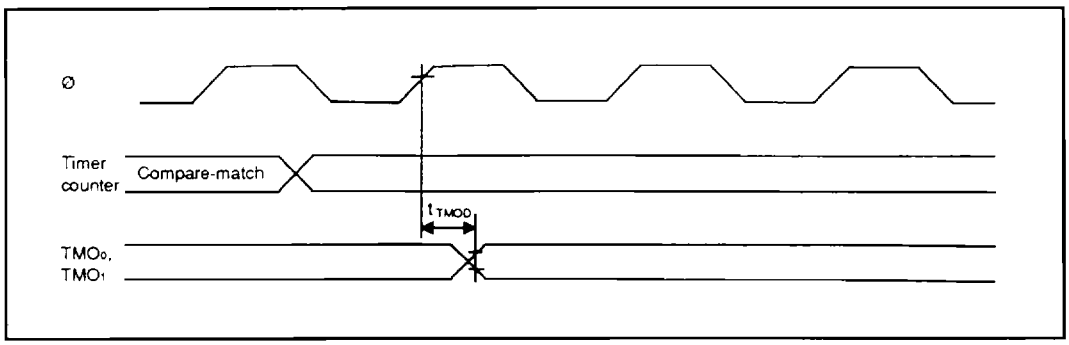

Figure 16-12. 8-Bit Timer Output Timing

(2) 8-Bit Timer Clock Input Timing

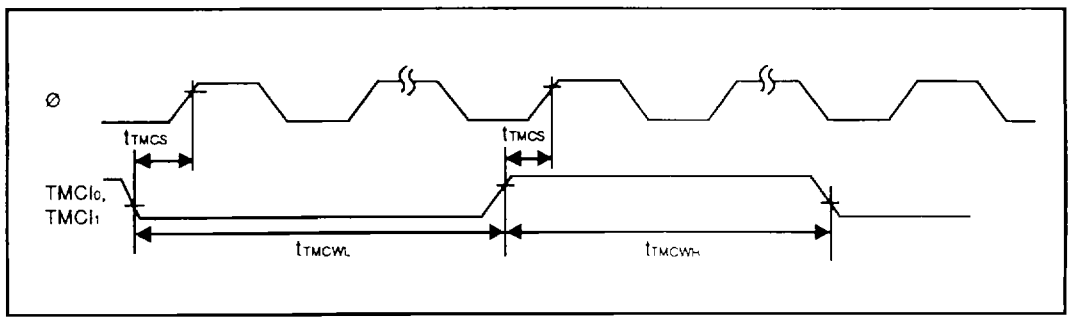

Figure 16-13. 8-Bit Timer Clock Input Timing

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(3) 8-Bit Timer Reset Input Timing

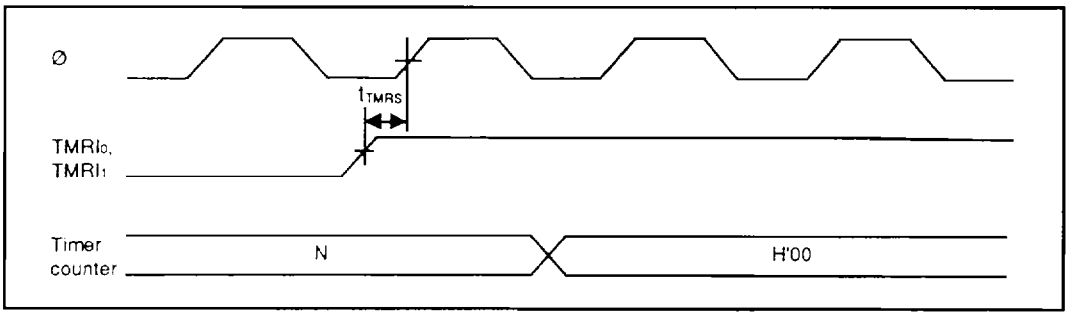

Figure 16-14. 8-Bit Timer Reset Input Timing

16.3.5 Pulse Width Modulation Timer Timing

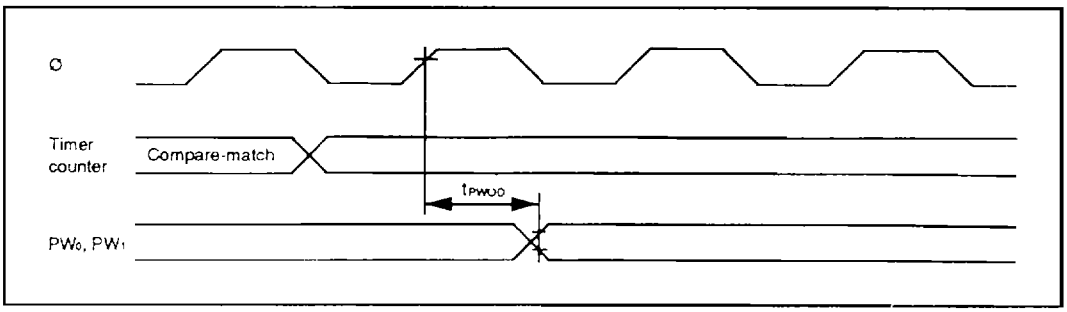

Figure 16-15. PWM Timer Output Timing

16.3.6 Serial Communication Interface Timing

(1) SCI Input/Output Timing

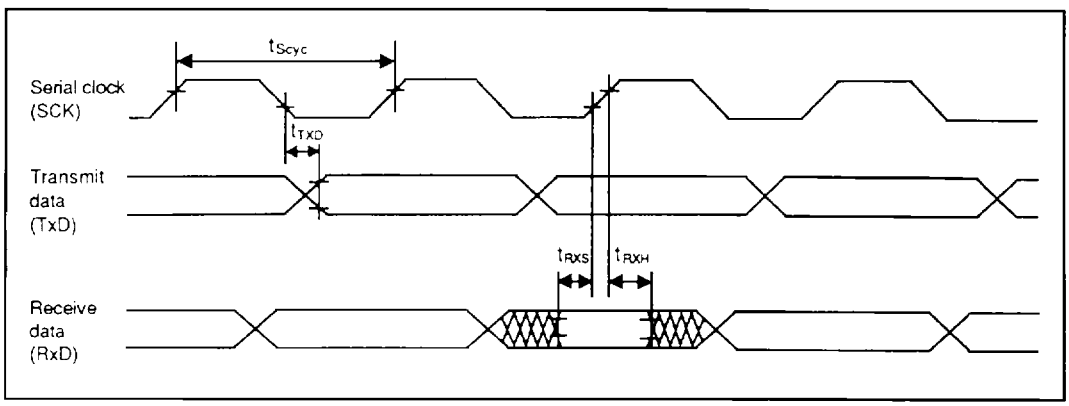

Figure 16-16. SCI Input/Output Timing (Synchronous Mode)

(2) SCI Input Clock Timing

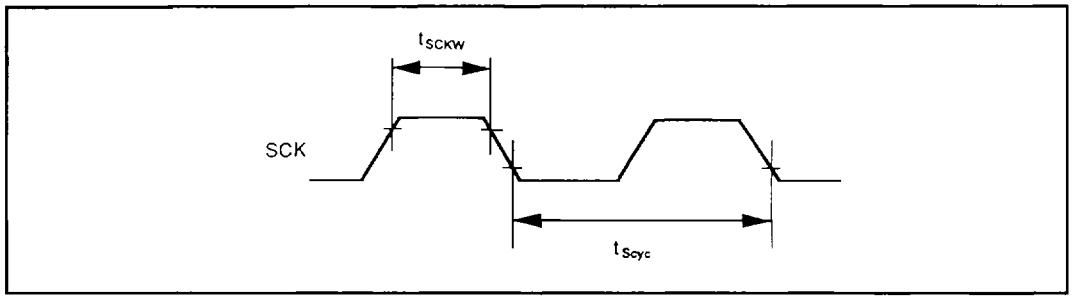

Figure 16-17. SCI Input Clock Timing

16.3.7 I/O Port Timing

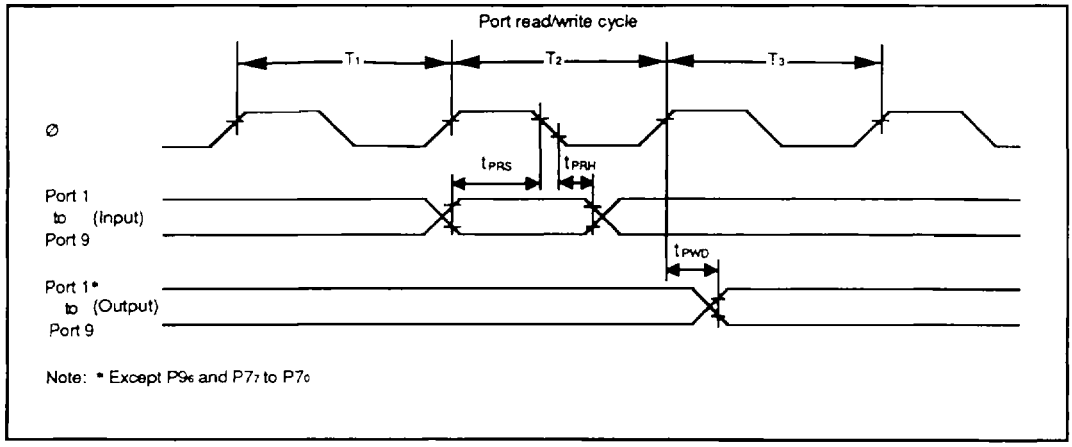

Figure 16-18. I/O Port Input/Output Timing

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